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Pixus Announces OpenVPX Development ATR Enclosure

Waterloo, Ontario — Sept 6, 2017 – Pixus Technologies, a provider of embedded computing and enclosure solutions, now offers a low-cost demonstration and development ATR (Air Transport Rack) for conduction-cooled 3U or 6U OpenVPX systems. The enclosure includes an external fan for supplemental cooling of high-power cards.

The ATRD058HEX-3U features a 6-slot 3U OpenVPX backplane to PCIe Gen3 (8 Gbps) speeds and includes a VITA 62 power supply slot. Other backplane slot sizes and various VITA 65 profiles are available. The development unit is slightly wider than a 1/2 ATR, Short.

The conduction cooled ATR with heat exchange features internal long fins to expel heat conductively. To provide more heat dissipation, a rear fan pulls air over the fins from a slotted outer shell. Therefore, the chassis is fully sealed, but provides enhanced cooling. The enclosure cools a minimum of 375W in the 3U OpenVPX ATR format with options for a 6U version upon request. Implementations providing up to 600W can be customized with additional thermal management provisions.

Pixus also offers standard air-cooled chassis in both rugged and commercial types. The company further provides OpenVPX backplanes, front panel/handle sets, and accessories.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.